

### **General Description**

The NVTFWS008N04C use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.This device is specially designed to get better ruggedness and suitable.

#### **General Features**

V<sub>DS</sub> =40V I<sub>D</sub> =60 A

 $R_{DS(ON)} < 8.5 m\Omega @ V_{GS} = 10V$ 

## Applications

Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications

### **Package Marking and Ordering Information**

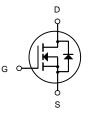
Product ID	Pack	Brand	Qty(PCS)
NVTFWS008N04C	DFN3X3-8L	HXY MOSFET	5000

### Absolute Maximum Ratings at T<sub>j</sub>=25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	VDS	40	V
Gate source voltage	VGS	±20	V
Continuous drain current <sup>1)</sup>	ID	60	А
Pulsed drain current <sup>2)</sup>	ID, pulse	130	А
Power dissipation <sup>3)</sup>	PD	39	W
Single pulsed avalanche energy <sup>5)</sup>	EAS	48	mJ
Operation and storage temperature	Tstg, Tj	-55 to 150	°C
Thermal resistance, junction-case	RθJC	3.2	°C/W
Thermal resistance, junction-ambient <sup>4)</sup>	RθJA	60	°C/W







N-Channel MOSFET



### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40			V
R <sub>DS(ON)</sub> St	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =12A		6.9	8.5	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		10.0	15	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.35		3	V
I <sub>DSS</sub> D	Drain-Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	uA
		V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , TJ=55℃			5	
lgss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)			5.8		
Qgs	Gate-Source Charge	V <sub>DS</sub> =20V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =12A		3		nC
$Q_{gd}$	Gate-Drain Charge			1.2		
T <sub>d(on)</sub>	Turn-On Delay Time			14.3		
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		5.6		
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =1A		20		ns
T <sub>f</sub>	Fall Time			11		
Ciss	Input Capacitance			690		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		193		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			38		
ls	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current			60	Α
Vsd	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃			1	V

Note :

1. The data tested by surface mounted on a 1 inch $^2$  FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%

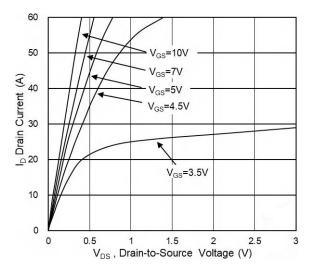
3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =31A 4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.



# NVTFWS008N04C N-SGT Enhancement Mode MOSFET

### **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

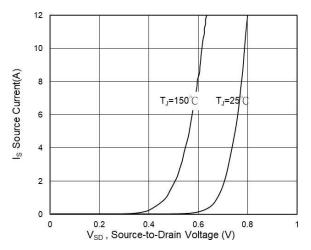


Fig.3 Source Drain Forward Characteristics

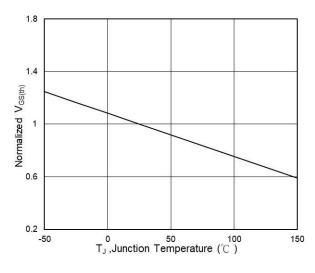


Fig.5 Normalized  $V_{GS(th)}\,vs\;T_J$ 

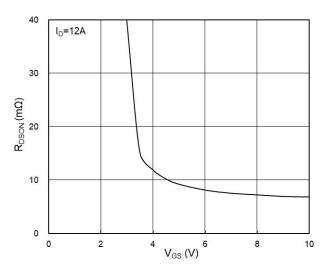


Fig.2 On-Resistance vs G-S Voltage

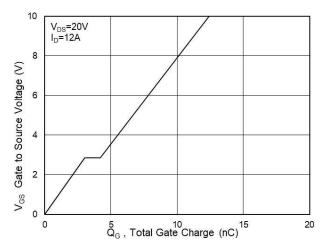


Fig.4 Gate-Charge Characteristics

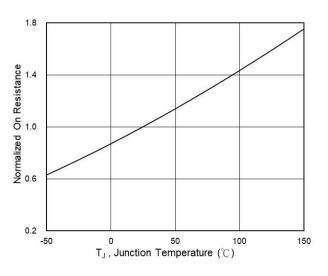
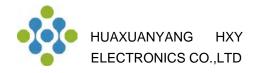
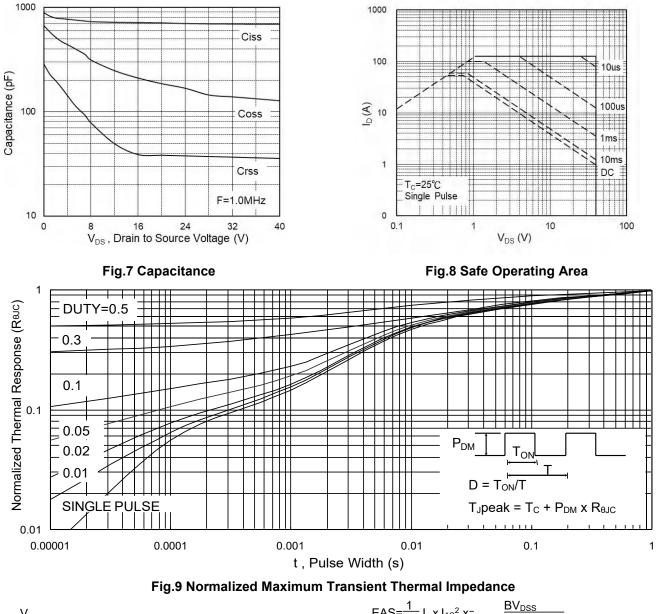
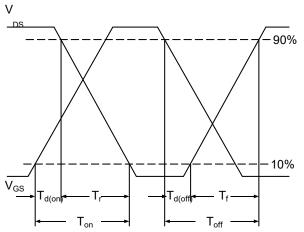


Fig.6 Normalized RDSON vs TJ



# NVTFWS008N04C N-SGT Enhancement Mode MOSFET





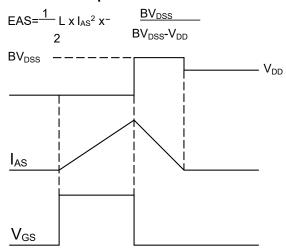
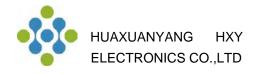
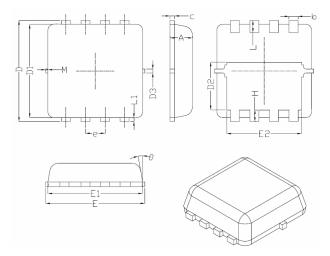


Fig.11 Unclamped Inductive Waveform



# DFN3X3-8L Package Information



Querra ha al	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
e	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
М	*	*	0.15	
θ		10 <sup>°</sup>	12 <sup>°</sup>	



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